

**MEMS Investor Journal and MEPTEC
3rd Annual MEMS Testing and Reliability Conference
Thursday, October 20, 2011 / Biltmore Hotel, Santa Clara, CA**

AGENDA

7:45 am Registration opens

8:30 am Welcome and Introduction

8:45 am – 9:30 am Cost of MEMS Testing: A Strategic Perspective
Mårten Vrånes, Director, MEMS Testing and Reliability, Consulting Services Group, MEMS Investor Journal, Inc.

9:30 am – 10:15 am Semiconductor Wafer Test Technology and Trends: Lessons for MEMS Test Engineers
Ira Feldman, Principal Consultant, Feldman Engineering Corp.

10:15 am – 10:45 am Break and Exhibits

10:45 am - 11:30 am The Role of Test Data Analysis in Taking MEMS Devices from Initial Characterization to Volume Production
Dan King, Senior Applications Engineer, Galaxy Semiconductor Solutions

11:30 am – 12:15 pm Operational Reliability of RF MEMS Relays
Daniel Hyman, President, XCOM Wireless, Inc.

12:15 pm – 1:15 pm Lunch and Exhibits

1:15 pm – 2:00 pm Automotive MEMS Pressure Sensor Reliability Testing
Tom Nguyen, Founder and CEO, AVsensors, Inc.

2:00 pm – 2:45 pm Bonding Reliability Testing for Wafer-Level Packaged MEMS Devices
Michael Shillinger, VP of Operations, Innovative Micro Technology, Inc.

2:45 pm – 3:15 pm Break and Exhibits

3:15 pm – 4:00 pm Optical Measurement Techniques for MEMS Characterization
Eric Lawrence, MEMS Business Development Manager, Polytec Inc.

4:00 pm – 4:45 pm Increased Yield and Reliability of Packaged MEMS Resonator Devices
Carl Arft, Director, Test Development Engineering, SiTime Corporation

4:45 pm – 5:00 pm Wrap up / additional questions

5:00 pm – 6:00 pm Reception
